# VSMY98545



**Vishay Semiconductors** 

# High Power Infrared Emitting Diode, 850 nm, **Surface Emitter Technology**



### **FEATURES**

- · Package type: surface mount
- · Package form: high power SMD with lens
- Dimensions (L x W x H in mm): 3.85 x 3.85 x 2.24
- Peak wavelength:  $\lambda_p = 850 \text{ nm}$
- · High reliability
- · High radiant power
- High radiant intensity
- Angle of half intensity:  $\varphi = \pm 45^{\circ}$
- · Low forward voltage
- Designed for high drive currents: up to 1 A (DC) and up to 5 A pulses
- Low thermal resistance: R<sub>th.IP</sub> = 10 K/W
- Floor life: 168 h, MSL 3, according to J-STD-020
- · Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### **APPLICATIONS**

- Infrared illumination for CMOS cameras (CCTV)
- Illumination for cameras (3D gaming)
- Machine vision
- 3D TV

# DESCRIPTION

As part of the <u>SurfLight<sup>TM</sup></u> portfolio, the VSMY98545 is an infrared, 850 nm emitting diode based on surface emitter technology with high radiant power and high speed, molded in low thermal resistance SMD package with lens. A 42 mil chip provides outstanding low forward voltage and allows DC operation of the device up to 1 A.

### 

PRODUCT SUMMARY				
COMPONENT	l <sub>e</sub> (mW/sr)	φ (deg)	λ <sub>p</sub> (nm)	t <sub>r</sub> (ns)
VSMY98545	350	± 45	850	15

#### Note

Test conditions see table "Basic Characteristics"

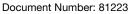
ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMY98545	Tape and reel	MOQ: 600 pcs, 600 pcs/reel	High power with lens		

#### Note

MOQ: minimum order quantity

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V <sub>R</sub>	5	V	
Forward current		I <sub>F</sub>	1	A	
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I <sub>FM</sub>	2	A	
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	5	A	
Power dissipation		Pv	2.3	W	
Junction temperature		Τj	125	°C	
Operating temperature range		T <sub>amb</sub>	-40 to +95	°C	
Storage temperature range		T <sub>stg</sub>	-40 to +100	°C	
Soldering temperature	Acc. figure 10, J-STD-20	T <sub>sd</sub>	260	°C	
Thermal resistance junction/pin	Acc. J-STD-051, soldered on PCB	R <sub>thJP</sub>	10	K/W	

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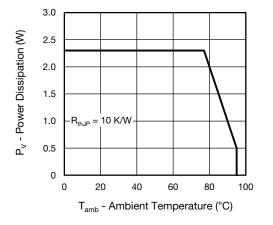


GREEN

(5-2008)



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Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

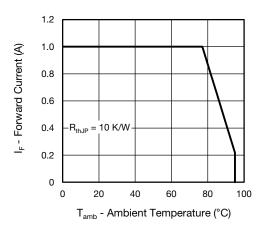


Fig. 2 - Forward Current Limit vs. Ambient Temperature

<b>BASIC CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 1 A, t <sub>p</sub> = 20 ms	V <sub>F</sub>		1.8	2.3	V
	I <sub>F</sub> = 5 A, t <sub>p</sub> = 100 μs	V <sub>F</sub>		3.3		V
Temperature coefficient of $V_F$	I <sub>F</sub> = 1 A	TK <sub>VF</sub>		-0.74		mV/K
Reverse current	V <sub>R</sub> = 5 V	I <sub>R</sub>	not designed for reverse operation			μA
Dedient intensity	I <sub>F</sub> = 1 A, t <sub>p</sub> = 20 ms	I <sub>e</sub>	230	350	550	mW/sr
Radiant intensity	I <sub>F</sub> = 5 A, t <sub>p</sub> = 100 μs	I <sub>e</sub>		1600		mW/sr
Radiant power	I <sub>F</sub> = 1 A, t <sub>p</sub> = 20 ms	фе		660		mW
Temperature coefficient of $\phi_{e}$	I <sub>F</sub> = 1 A	TKφ <sub>e</sub>		-0.14		%/K
Angle of half intensity		φ		± 45		deg
Peak wavelength	I <sub>F</sub> = 1 A	λρ		850		nm
Spectral bandwidth	I <sub>F</sub> = 1 A	Δλ		30		nm
Temperature coefficient of $\lambda_p$	I <sub>F</sub> = 1 A	TKλ <sub>p</sub>		0.2		nm/K
Rise time	I <sub>F</sub> = 1 A	t <sub>r</sub>		15		ns
Fall time	I <sub>F</sub> = 1 A	t <sub>f</sub>		18		ns



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### BASIC CHARACTERISTICS (T<sub>amb</sub> = 25 °C, unless otherwise specified)

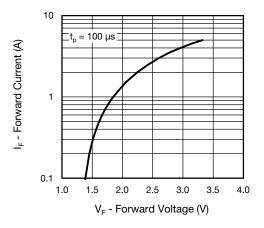


Fig. 3 - Forward Current vs. Forward Voltage

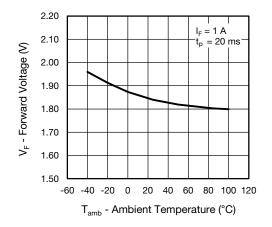


Fig. 4 - Forward Voltage vs. Ambient Temperature

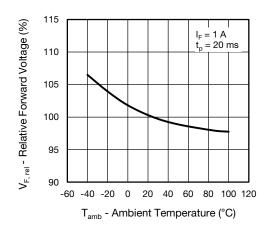


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

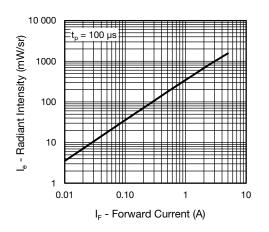


Fig. 6 - Radiant Intensity vs. Forward Current

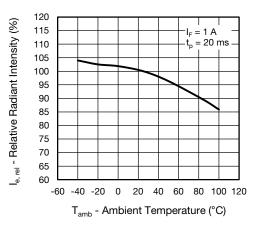


Fig. 7 - Relative Radiant Intensity vs. Ambient Temperature

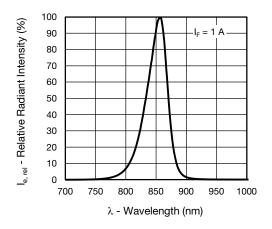


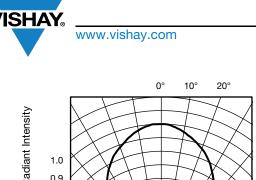
Fig. 8 - Relative Radiant Power vs. Wavelength

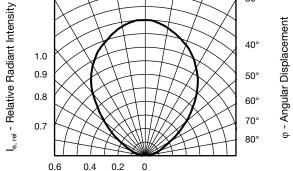
3 estions, contact: emittertechsupport@

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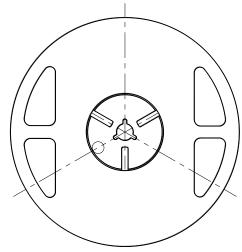


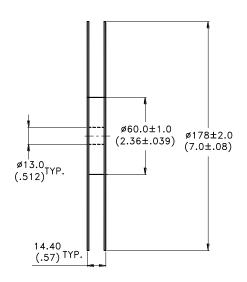


30°

Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

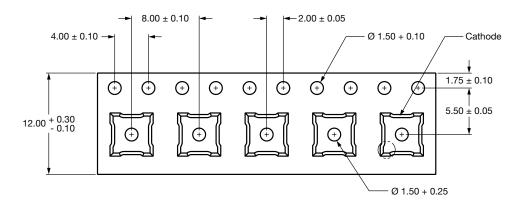
#### **TAPING DIMENSIONS** in millimeters





#### Notes

- Empty component pockets sealed with top cover tape.
- 7 inch reel 600 pieces per reel.
- The maximum number of consecutive missing lamps is two.
- In accordance with ANSI/EIA 481-1-A-1994 specifications.



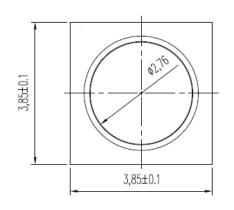
4 For technical questions, contact: <u>emittertechsupport@vishay.com</u> Document Number: 81223

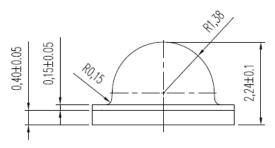
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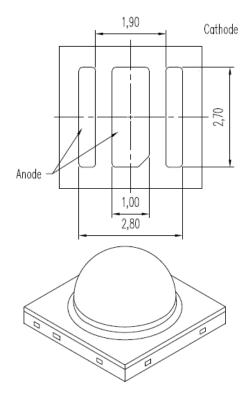




### **PACKAGE DIMENSIONS** in millimeters

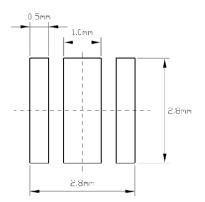






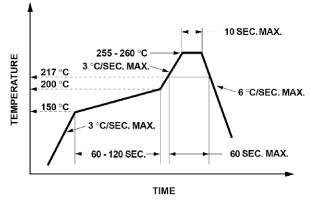
#### Notes

- Tolerance is  $\pm$  0.10 mm (0.004") unless otherwise noted.
- Specifications are subject to change without notice.



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### SOLDER PROFILE



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Fig. 10 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

#### DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

### FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions:  $T_{amb}$  < 30 °C, RH < 60 %

Moisture sensitivity level 3, acc. to J-STD-020B

#### DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.



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